

## Micropower Voltage Detector

### Features

- Ultra-Low Supply Current: 1.75  $\mu$ A (Max.)
- Precision Monitoring Options Of:
  - 1.90V, 2.32V, 2.63V, 2.90V, 2.93V, 3.08V, 4.38V and 4.63V
- Resets Microcontroller in a Power-Loss Event
- Active-Low  $V_{OUT}$  Pin:
  - **MCP111** Active-Low, Open-Drain
  - **MCP112** Active-Low, Push-Pull
- Available in SOT23-3, TO-92, SC-70 and SOT-89-3 Packages
- Temperature Range:
  - Extended: -40°C to +125°C (except MCP1XX-195)
  - Industrial: -40°C to +85°C (MCP1XX-195 Only)
- Pb-Free Devices

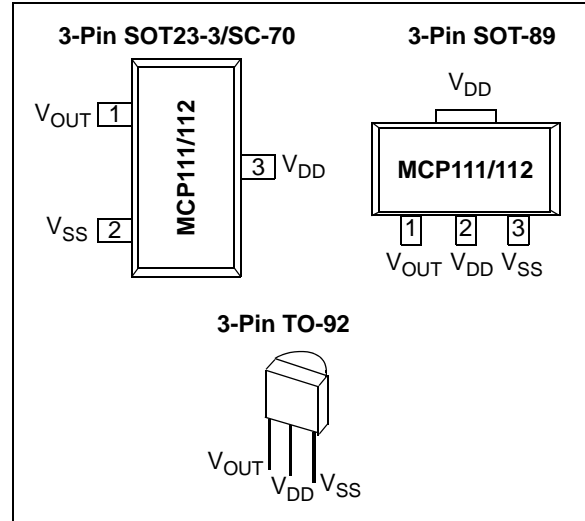
### Applications

- Critical Microcontroller and Microprocessor Power-Monitoring Applications
- Computers
- Intelligent Instruments
- Portable Battery-Powered Equipment

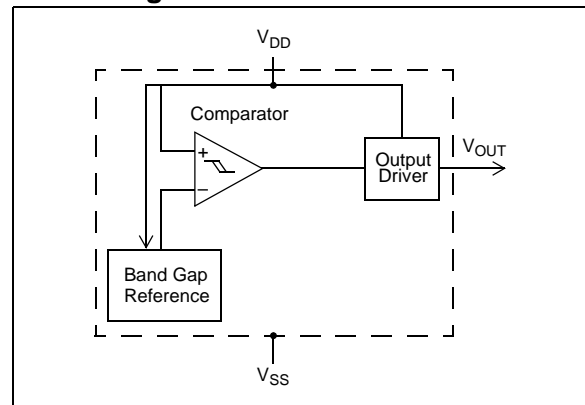
### General Description

The MCP111/112 are voltage-detecting devices designed to keep a microcontroller in reset until the system voltage has stabilized at the appropriate level for reliable system operation. These devices also operate as protection from brown-out conditions when the system supply voltage drops below the specified threshold voltage level. Eight different trip voltages are available.

### Package Types



### Block Diagram



### DEVICE FEATURES

Device	Output		Reset Delay (typ.)	SOT-23/SC70 Package Pin Out (Pin # 1, 2, 3)	Comment
	Type	Pull-up Resistor			
MCP111	Open-drain	External	No	$V_{OUT}, V_{SS}, V_{DD}$	
MCP112	Push-pull	No	No	$V_{OUT}, V_{SS}, V_{DD}$	
MCP102	Push-pull	No	120 ms	$\overline{RST}, V_{DD}, V_{SS}$	See <b>MCP102/103/121/131</b> Data Sheet (DS20001906)
MCP103	Push-pull	No	120 ms	$V_{SS}, \overline{RST}, V_{DD}$	See <b>MCP102/103/121/131</b> Data Sheet (DS20001906)
MCP121	Open-drain	External	120 ms	$\overline{RST}, V_{DD}, V_{SS}$	See <b>MCP102/103/121/131</b> Data Sheet (DS20001906)
MCP131	Open-Drain	Internal (~95 k $\Omega$ )	120 ms	$\overline{RST}, V_{DD}, V_{SS}$	See <b>MCP102/103/121/131</b> Data Sheet (DS20001906)

# MCP111/112

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings†

$V_{DD}$ .....	7.0V
Input current ( $V_{DD}$ ) .....	10 mA
Output current ( $RST$ ) .....	10 mA
Rated Rise Time of $V_{DD}$ .....	100V/ $\mu$ s
All inputs and outputs (except $RST$ ) w.r.t. $V_{SS}$ .....	-0.6V to ( $V_{DD} + 1.0V$ )
$RST$ output w.r.t. $V_{SS}$ .....	-0.6V to 13.5V
Storage temperature .....	65°C to + 150°C
Ambient temp. with power applied .....	-40°C to + 125°C
Maximum Junction temp. with power applied .....	150°C
ESD protection on all pins .....	$\geq 2$ kV

† **Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### DC CHARACTERISTICS

**Electrical Specifications:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to 5.5V,  $R_{PU} = 100$  k $\Omega$  (only MCP111),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .

Parameters		Symbol	Min.	Typ.	Max.	Units	Conditions
Operating Voltage Range		$V_{DD}$	1.0	—	5.5	V	
Specified $V_{DD}$ Value to $V_{OUT}$ low		$V_{DD}$	1.0	—		V	$I_{RST} = 10 \mu\text{A}$ , $V_{RST} < 0.2V$
Operating Current		$I_{DD}$	—	< 1	1.75	$\mu\text{A}$	
$V_{DD}$ Trip Point	MCP1XX-195	$V_{TRIP}$	1.872	1.900	1.929	V	$T_A = +25^\circ\text{C}$ (Note 1)
			1.853	1.900	1.948	V	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (Note 2)
	MCP1XX-240		2.285	2.320	2.355	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.262	2.320	2.378	V	Note 2
	MCP1XX-270		2.591	2.630	2.670	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.564	2.630	2.696	V	Note 2
	MCP1XX-290		2.857	2.900	2.944	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.828	2.900	2.973	V	Note 2
	MCP1XX-300		2.886	2.930	2.974	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.857	2.930	3.003	V	Note 2
	MCP1XX-315		3.034	3.080	3.126	V	$T_A = +25^\circ\text{C}$ (Note 1)
			3.003	3.080	3.157	V	Note 2
	MCP1XX-450		4.314	4.380	4.446	V	$T_A = +25^\circ\text{C}$ (Note 1)
4.271		4.380	4.490	V	Note 2		
MCP1XX-475	4.561	4.630	4.700	V	$T_A = +25^\circ\text{C}$ (Note 1)		
	4.514	4.630	4.746	V	Note 2		
$V_{DD}$ Trip Point Tempco		$T_{TPCO}$	—	$\pm 100$	—	ppm/ $^\circ\text{C}$	

- Note 1:** Trip point is  $\pm 1.5\%$  from typical value.  
**Note 2:** Trip point is  $\pm 2.5\%$  from typical value.  
**Note 3:** This specification allows this device to be used in PIC<sup>®</sup> microcontroller applications that require the In-Circuit Serial Programming<sup>™</sup> (ICSP<sup>™</sup>) feature (see device-specific programming specifications for voltage requirements). This specification DOES NOT allow a continuous high voltage to be present on the open-drain output pin ( $V_{OUT}$ ). The total time that the  $V_{OUT}$  pin can be above the maximum device operational voltage (5.5V) is 100 sec. Current into the  $V_{OUT}$  pin should be limited to 2 mA. It is recommended that the device operational temperature be maintained between 0°C to 70°C (+25°C preferred). For additional information, please refer to [Figure 2-28](#).  
**Note 4:** This parameter is established by characterization and is not 100% tested.

## DC CHARACTERISTICS (CONTINUED)

**Electrical Specifications:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to  $5.5V$ ,  $R_{PU} = 100\text{ k}\Omega$  (only **MCP111**),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .

Parameters		Symbol	Min.	Typ.	Max.	Units	Conditions
Threshold Hysteresis (min. = 1%, max = 6%)	<b>MCP1XX-195</b>	$V_{HYS}$	0.019	—	0.114	V	$T_A = +25^\circ\text{C}$
	<b>MCP1XX-240</b>		0.023	—	0.139	V	
	<b>MCP1XX-270</b>		0.026	—	0.158	V	
	<b>MCP1XX-290</b>		0.029	—	0.174	V	
	<b>MCP1XX-300</b>		0.029	—	0.176	V	
	<b>MCP1XX-315</b>		0.031	—	0.185	V	
	<b>MCP1XX-450</b>		0.044	—	0.263	V	
	<b>MCP1XX-475</b>		0.046	—	0.278	V	
$V_{OUT}$ Low-level Output Voltage		$V_{OL}$	—	—	0.4	V	$I_{OL} = 500\text{ }\mu\text{A}$ , $V_{DD} = V_{TRIP(MIN)}$
$V_{OUT}$ High-level Output Voltage		$V_{OH}$	$V_{DD} - 0.6$	—	—	V	$I_{OH} = 1\text{ mA}$ , For only <b>MCP112</b> (push-pull output)
Open-drain High Voltage on Output		$V_{ODH}$	—	—	13.5 <sup>(3)</sup>	V	<b>MCP111</b> only, $V_{DD} = 3.0V$ , Time voltage > 5.5V applied $\leq 100s$ , current into pin limited to 2 mA, $+25^\circ\text{C}$ operation recommended <a href="#">Note 3</a> , <a href="#">Note 4</a>
Open-drain Output Leakage Current ( <b>MCP111</b> only)		$I_{OD}$	—	0.1	—	$\mu\text{A}$	

- Note 1:** Trip point is  $\pm 1.5\%$  from typical value.
- Note 2:** Trip point is  $\pm 2.5\%$  from typical value.
- Note 3:** This specification allows this device to be used in PIC<sup>®</sup> microcontroller applications that require the In-Circuit Serial Programming™ (ICSP™) feature (see device-specific programming specifications for voltage requirements). This specification DOES NOT allow a continuous high voltage to be present on the open-drain output pin ( $V_{OUT}$ ). The total time that the  $V_{OUT}$  pin can be above the maximum device operational voltage (5.5V) is 100 sec. Current into the  $V_{OUT}$  pin should be limited to 2 mA. It is recommended that the device operational temperature be maintained between  $0^\circ\text{C}$  to  $70^\circ\text{C}$  ( $+25^\circ\text{C}$  preferred). For additional information, please refer to [Figure 2-28](#).
- Note 4:** This parameter is established by characterization and is not 100% tested.

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**FIGURE 1-1:** Timing Diagram.

## AC CHARACTERISTICS

**Electrical Specifications:** Unless otherwise indicated, all limits are specified for V<sub>DD</sub> = 1V to 5.5V, R<sub>PU</sub> = 100 kΩ (only MCP111), T<sub>A</sub> = -40°C to +125°C.

Parameters	Symbol	Min.	Typ.	Max.	Units	Conditions
V <sub>DD</sub> Detect to V <sub>OUT</sub> Inactive	t <sub>RPU</sub>	—	90	—	μs	Figure 1-1 and C <sub>L</sub> = 50 pF (Note 1)
V <sub>DD</sub> Detect to V <sub>OUT</sub> Active	t <sub>RPD</sub>	—	130	—	μs	V <sub>DD</sub> ramped from V <sub>TRIP(MAX)</sub> + 250 mV down to V <sub>TRIP(MIN)</sub> - 250 mV, per Figure 1-1, C <sub>L</sub> = 50 pF (Note 1)
V <sub>OUT</sub> Rise Time After V <sub>OUT</sub> Active	t <sub>RT</sub>	—	5	—	μs	For V <sub>OUT</sub> 10% to 90% of final value per Figure 1-1, C <sub>L</sub> = 50 pF (Note 1)

**Note 1:** These parameters are for design guidance only and are not 100% tested.

## TEMPERATURE CHARACTERISTICS

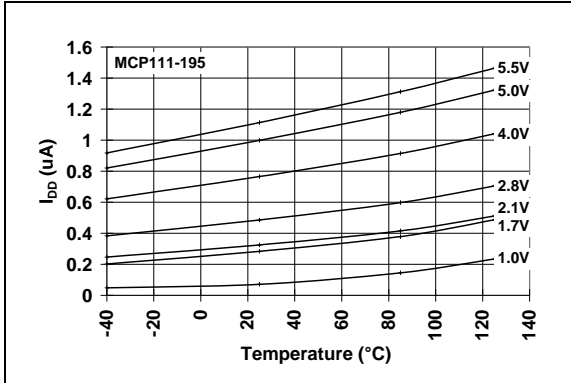
**Electrical Specifications:** Unless otherwise noted, all limits are specified for V<sub>DD</sub> = 1V to 5.5V, R<sub>PU</sub> = 100 kΩ (MCP111 only), T<sub>A</sub> = -40°C to +125°C.

Parameters	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>Temperature Ranges</b>						
Specified Temperature Range	T <sub>A</sub>	-40	—	+85	°C	MCP1XX-195
Specified Temperature Range	T <sub>A</sub>	-40	—	+125	°C	Except MCP1XX-195
Maximum Junction Temperature	T <sub>J</sub>	—	—	+150	°C	
Storage Temperature Range	T <sub>A</sub>	-65	—	+150	°C	
<b>Package Thermal Resistances</b>						
Thermal Resistance, 3L-SOT23	θ <sub>JA</sub>	—	336	—	°C/W	
Thermal Resistance, 3L-SC-70	θ <sub>JA</sub>	—	340	—	°C/W	
Thermal Resistance, 3L-TO-92	θ <sub>JA</sub>	—	131.9	—	°C/W	
Thermal Resistance, 3L-SOT-89	θ <sub>JA</sub>	—	110	—	°C/W	

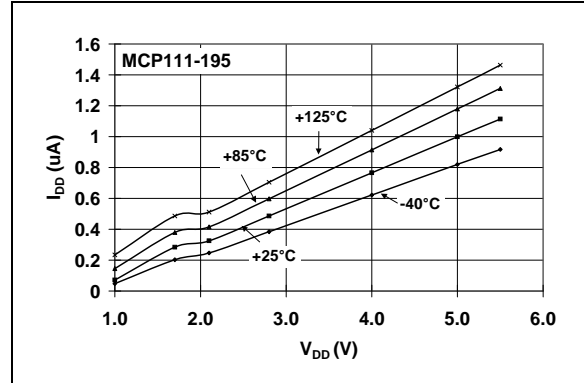
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

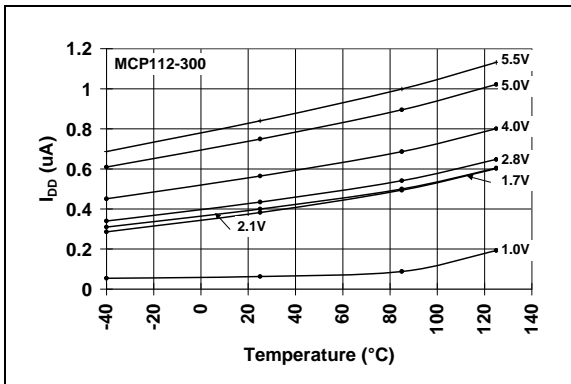
**Note:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to  $5.5V$ ,  $R_{PU} = 100\text{ k}\Omega$  (only **MCP111**; see **Figure 4-1**),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .



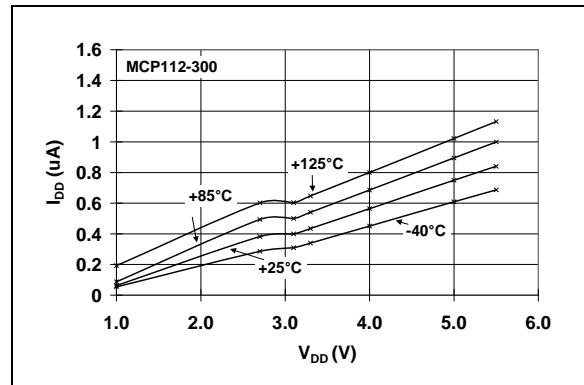
**FIGURE 2-1:**  $I_{DD}$  vs. Temperature (MCP111-195).



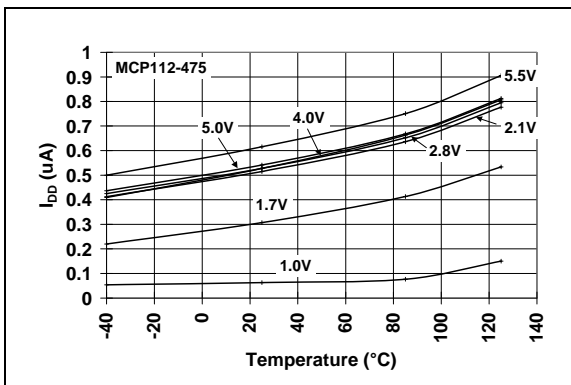
**FIGURE 2-4:**  $I_{DD}$  vs.  $V_{DD}$  (MCP111-195).



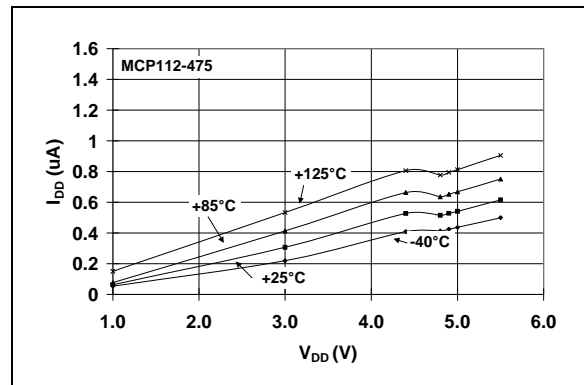
**FIGURE 2-2:**  $I_{DD}$  vs. Temperature (MCP112-300).



**FIGURE 2-5:**  $I_{DD}$  vs.  $V_{DD}$  (MCP112-300).



**FIGURE 2-3:**  $I_{DD}$  vs. Temperature (MCP112-475).



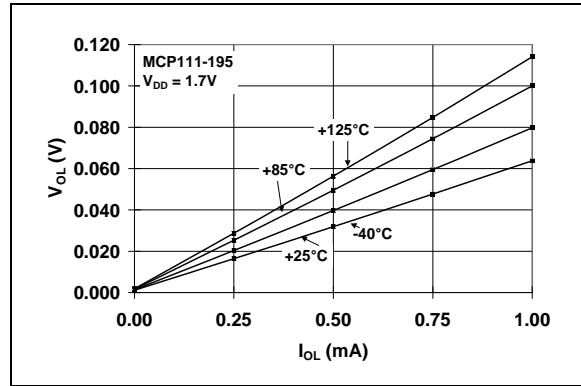
**FIGURE 2-6:**  $I_{DD}$  vs.  $V_{DD}$  (MCP112-475).

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**Note:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to  $5.5V$ ,  $R_{PU} = 100\text{ k}\Omega$  (only MCP111; see Figure 4-1),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .



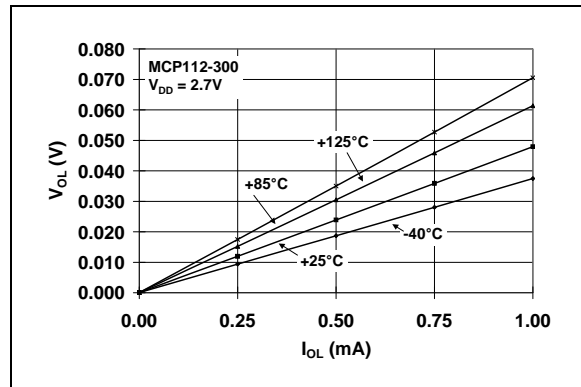
**FIGURE 2-7:**  $V_{TRIP}$  and  $V_{HYST}$  vs. Temperature (MCP111-195).



**FIGURE 2-10:**  $V_{OL}$  vs.  $I_{OL}$  (MCP111-195 @  $V_{DD} = 1.7V$ ).



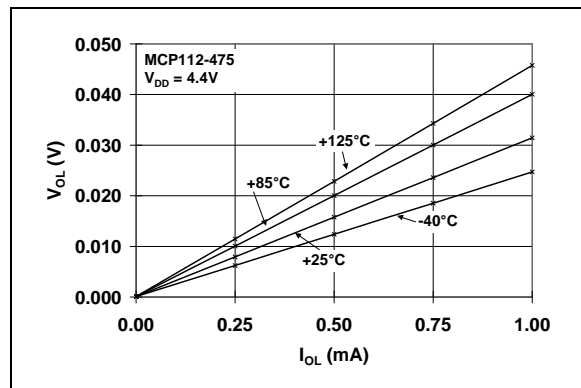
**FIGURE 2-8:**  $V_{TRIP}$  and  $V_{HYST}$  vs. Temperature (MCP112-300).



**FIGURE 2-11:**  $V_{OL}$  vs.  $I_{OL}$  (MCP112-300 @  $V_{DD} = 2.7V$ ).



**FIGURE 2-9:**  $V_{TRIP}$  and  $V_{HYST}$  vs. Temperature (MCP112-475).



**FIGURE 2-12:**  $V_{OL}$  vs.  $I_{OL}$  (MCP112-475 @  $V_{DD} = 4.4V$ ).

**Note:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to  $5.5V$ ,  $R_{PU} = 100\text{ k}\Omega$  (only MCP111; see Figure 4-1),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .



**FIGURE 2-13:**  $V_{OL}$  vs. Temperature (MCP111-195 @  $V_{DD} = 1.7V$ ).



**FIGURE 2-16:**  $V_{OH}$  vs.  $I_{OH}$  (MCP112-300 @  $V_{DD} = 3.1V$ ).



**FIGURE 2-14:**  $V_{OL}$  vs. Temperature (MCP112-300 @  $V_{DD} = 2.7V$ ).



**FIGURE 2-17:**  $V_{OH}$  vs.  $I_{OH}$  (MCP112-475 @  $V_{DD} = 4.8V$ ).



**FIGURE 2-15:**  $V_{OL}$  vs. Temperature (MCP112-475 @  $V_{DD} = 4.4V$ ).



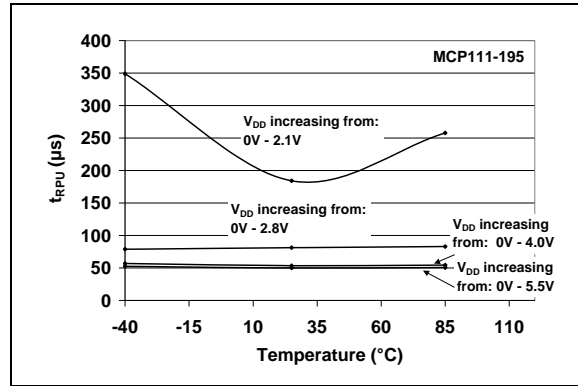
**FIGURE 2-18:** Typical Transient Response ( $25^\circ\text{C}$ ).

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**Note:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to  $5.5V$ ,  $R_{PU} = 100\text{ k}\Omega$  (only MCP111; see Figure 4-1),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .



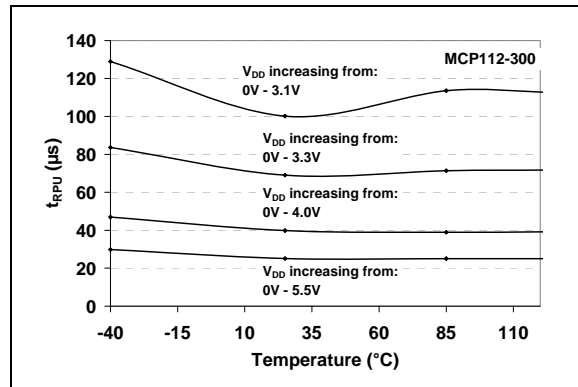
**FIGURE 2-19:**  $t_{RPD}$  vs. Temperature (MCP111-195).



**FIGURE 2-22:**  $t_{RPU}$  vs. Temperature (MCP111-195).



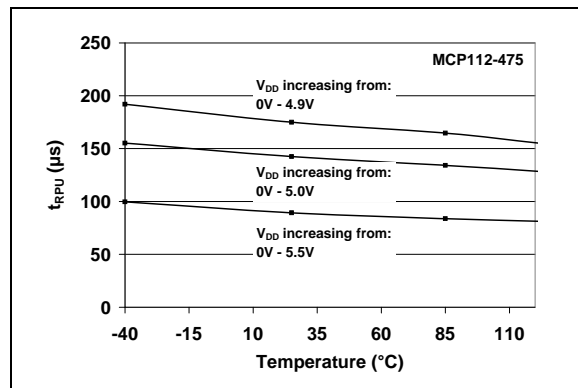
**FIGURE 2-20:**  $t_{RPD}$  vs. Temperature (MCP112-300).



**FIGURE 2-23:**  $t_{RPU}$  vs. Temperature (MCP112-300).

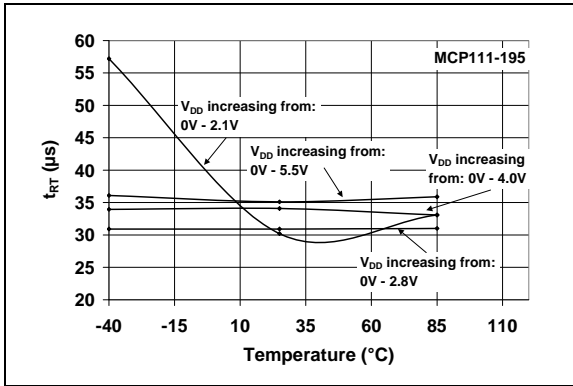


**FIGURE 2-21:**  $t_{RPD}$  vs. Temperature (MCP112-475).

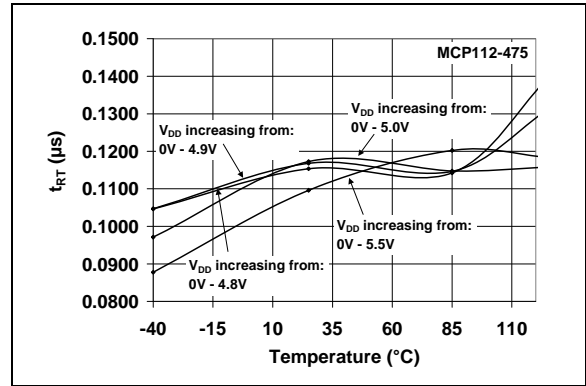


**FIGURE 2-24:**  $t_{RPU}$  vs. Temperature (MCP112-475).

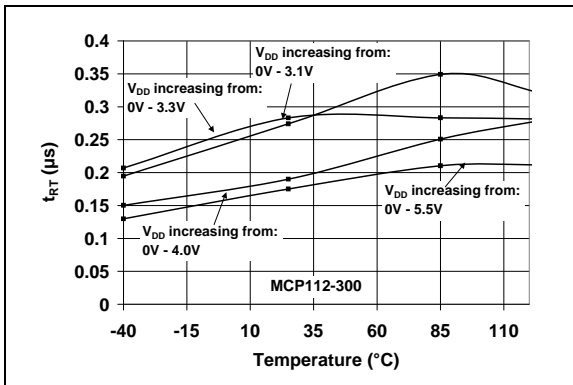
**Note:** Unless otherwise indicated, all limits are specified for  $V_{DD} = 1V$  to  $5.5V$ ,  $R_{PU} = 100\text{ k}\Omega$  (only MCP111; see Figure 4-1),  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .



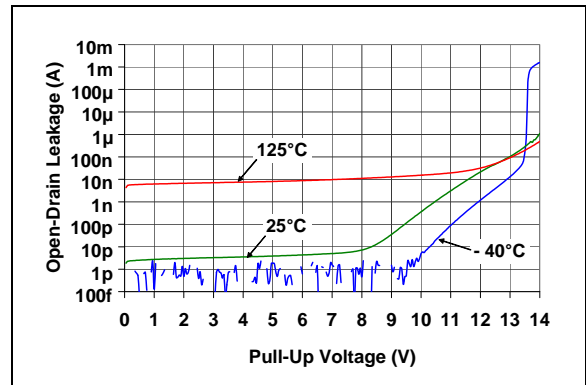
**FIGURE 2-25:**  $t_{RT}$  vs. Temperature (MCP111-195).



**FIGURE 2-27:**  $t_{RT}$  vs. Temperature (MCP112-475).



**FIGURE 2-26:**  $t_{RT}$  vs. Temperature (MCP112-300).



**FIGURE 2-28:** Open-Drain Leakage Current vs. Voltage Applied to  $V_{OUT}$  Pin (MCP111-195).

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## 3.0 PIN DESCRIPTION

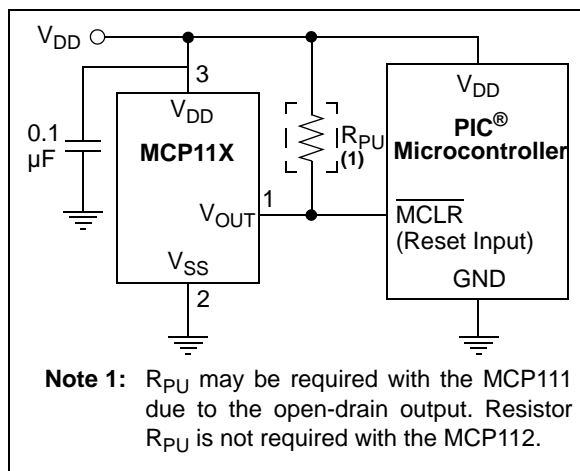
The descriptions of the pins are listed in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

Pin Number			Symbol	Function
SOT-23-3 SC-70	SOT-89-3	T0-92		
1	1	1	$V_{OUT}$	<b>Output State</b> <b><math>V_{DD}</math> Falling:</b> $H = V_{DD} > V_{TRIP}$ $L = V_{DD} < V_{TRIP}$  <b><math>V_{DD}</math> Rising:</b> $H = V_{DD} > V_{TRIP} + V_{HYS}$ $L = V_{DD} < V_{TRIP} + V_{HYS}$
2	3	3	$V_{SS}$	Ground reference
3	2	2	$V_{DD}$	Positive power supply
—	4	—	$V_{DD}$	Positive power supply

## 4.0 APPLICATION INFORMATION

For many of today's microcontroller applications, care must be taken to prevent low-power conditions that can cause many different system problems. The most common causes is a brown-out condition, where the system supply drops below the operating level momentarily. The second most common cause is when a slowly decaying power supply causes the microcontroller to begin executing instructions without sufficient voltage to sustain SRAM, thus producing indeterminate results. Figure 4-1 shows a typical application circuit.

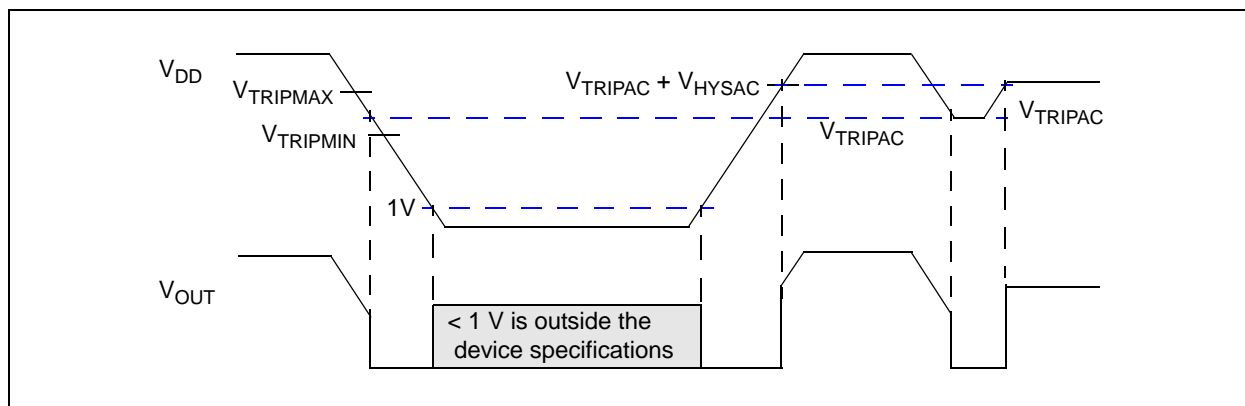


**FIGURE 4-1:** Typical Application Circuit.

## 4.1 $V_{TRIP}$ Operation

The voltage trip point ( $V_{TRIP}$ ) is determined on the falling edge of  $V_{DD}$ . The actual voltage trip point ( $V_{TRIPAC}$ ) will be between the minimum trip point ( $V_{TRIPMIN}$ ) and the maximum trip point ( $V_{TRIPMAX}$ ). There is a hysteresis on this trip point to remove any "jitter" that would occur on the  $V_{OUT}$  pin when the device  $V_{DD}$  is at the trip point.

Figure 4-2 shows the state of the  $V_{OUT}$  pin as determined by the  $V_{DD}$  voltage. The  $V_{TRIP}$  specification is for falling  $V_{DD}$  voltages. When the  $V_{DD}$  voltage is rising, the  $V_{OUT}$  pin will not be driven high until  $V_{DD}$  is at  $V_{TRIP} + V_{HYS}$ .



**FIGURE 4-2:**  $V_{OUT}$  Operation as Determined by the  $V_{TRIP}$  and  $V_{HYS}$ .

## 4.2 Negative Going $V_{DD}$ Transients

The minimum pulse width (time) required to cause a reset may be an important criteria in the implementation of a Power-on Reset (POR) circuit. This time is referred to as transient duration, defined as the amount of time needed for these supervisory devices to respond to a drop in  $V_{DD}$ . The transient duration time is dependent on the magnitude of  $V_{TRIP} - V_{DD}$ . Generally speaking, the transient duration decreases with increases in  $V_{TRIP} - V_{DD}$ .

Figure 4-3 shows a typical transient duration vs. reset comparator overdrive for which the MCP111/112 will not generate a reset pulse. It shows that the farther below the trip point the transient pulse goes, the duration of the pulse required to cause a reset gets shorter. Figure 2-18 shows the transient response characteristics for the MCP111/112.

A 0.1  $\mu\text{F}$  bypass capacitor, mounted as close as possible to the  $V_{DD}$  pin, provides additional transient immunity (refer to Figure 4-1).

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**FIGURE 4-3:** Example of Typical Transient Duration Waveform.

## 4.3 Effect of Temperature on Time-Out Period ( $t_{RPU}$ )

The time-out period ( $t_{RPU}$ ) determines how long the device remains in the reset condition. This is affected by both  $V_{DD}$  and temperature. The graph shown in Figures 2-22, 2-23 and 2-24 show the typical response for different  $V_{DD}$  values and temperatures.

## 4.4 Using in PIC<sup>®</sup> Microcontroller ICSP<sup>™</sup> Applications (MCP111 only)

Figure 4-4 shows the typical application circuit for using the MCP111 for voltage supervisory function when the PIC microcontroller will be programmed via the In-Circuit Serial Programming<sup>™</sup> (ICSP) feature. Additional information is available in TB087, “Using Voltage Supervisors with PIC<sup>®</sup> Microcontroller Systems which Implement In-Circuit Serial Programming<sup>™</sup>”, DS91087.

**Note:** It is recommended that the current into the  $\overline{RST}$  pin be current limited by a 1 k $\Omega$  resistor.



**FIGURE 4-4:** Typical Application Circuit for PIC<sup>®</sup> Microcontroller with the ICSP<sup>™</sup> feature.

## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

3-Lead TO-92



Device	Code
MCP111-240E/TO	240E
MCP111-270E/TO	270E
MCP111-290E/TO	290E
MCP111-300E/TO	300E
MCP111-315E/TO	315E
MCP111-450E/TO	450E
MCP111-475E/TO	475E
MCP111-195I/TO	195I

Example:



3-Lead SOT-23



Device	Code
MCP111T-195I/TT	MPNN
MCP111T-240ETT	MQNN
MCP111T-270E/TT	MGNN
MCP111T-290E/TT	NHNN
MCP111T-300E/TT	MJNN
MCP111T-315E/TT	MKNN
MCP111T-450E/TT	MLNN
MCP111T-475E/TT	MMNN
MCP112T-195I/TT	MRNN
MCP112T-240ETT	MSNN
MCP112T-270E/TT	MANN
MCP112T-290E/TT	MBNN
MCP112T-300E/TT	MCNN
MCP112T-315E/TT	MDNN
MCP112T-450E/TT	MENN
MCP112T-475E/TT	MFNN

Example:



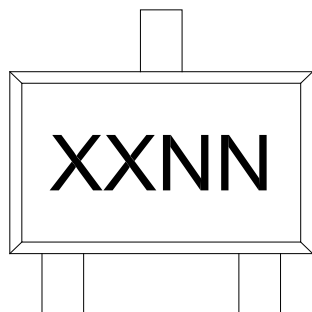
<b>Legend:</b>	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

# MCP111/112

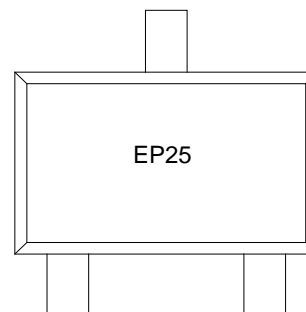
## Package Marking Information (Continued)

3-Lead SC-70



Device	Code
MCP111T-195I/LB	EPNN
MCP111T-240E/LB	EQNN
MCP111T-270E/LB	EGNN
MCP111T-290E/LB	EHNN
MCP111T-300E/LB	EJNN
MCP111T-315E/LB	EKNN
MCP111T-450E/LB	ELNN
MCP111T-475E/LB	EMNN
MCP112T-195I/LB	ERNN
MCP112T-240E/LB	ESNN
MCP112T-270E/LB	EANN
MCP112T-290E/LB	EBNN
MCP112T-300E/LB	ECNN
MCP112T-315E/LB	EDNN
MCP112T-450E/LB	EENN
MCP112T-475E/LB	EFNN

Example:

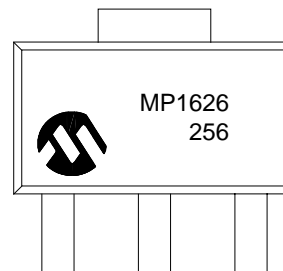


3-Lead SOT-89



Device	Code
MCP111T-195I/MB	MP
MCP111T-240EMB	MQ
MCP111T-270E/MB	MG
MCP111T-290E/MB	NH
MCP111T-300E/MB	MJ
MCP111T-315E/MB	MK
MCP111T-450E/MB	ML
MCP111T-475E/MB	MM
MCP112T-195I/MB	MR
MCP112T-240EMB	MS
MCP112T-270E/MB	MA
MCP112T-290E/MB	MB
MCP112T-300E/MB	MC
MCP112T-315E/MB	MD
MCP112T-450E/MB	ME
MCP112T-475E/MB	MF

Example:



## 3-Lead Plastic Transistor Outline (TO) [TO-92]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES	
		MIN	MAX
Number of Pins	N	3	
Pitch	e	.050 BSC	
Bottom to Package Flat	D	.125	.165
Overall Width	E	.175	.205
Overall Length	A	.170	.210
Molded Package Radius	R	.080	.105
Tip to Seating Plane	L	.500	–
Lead Thickness	c	.014	.021
Lead Width	b	.014	.022

**Notes:**

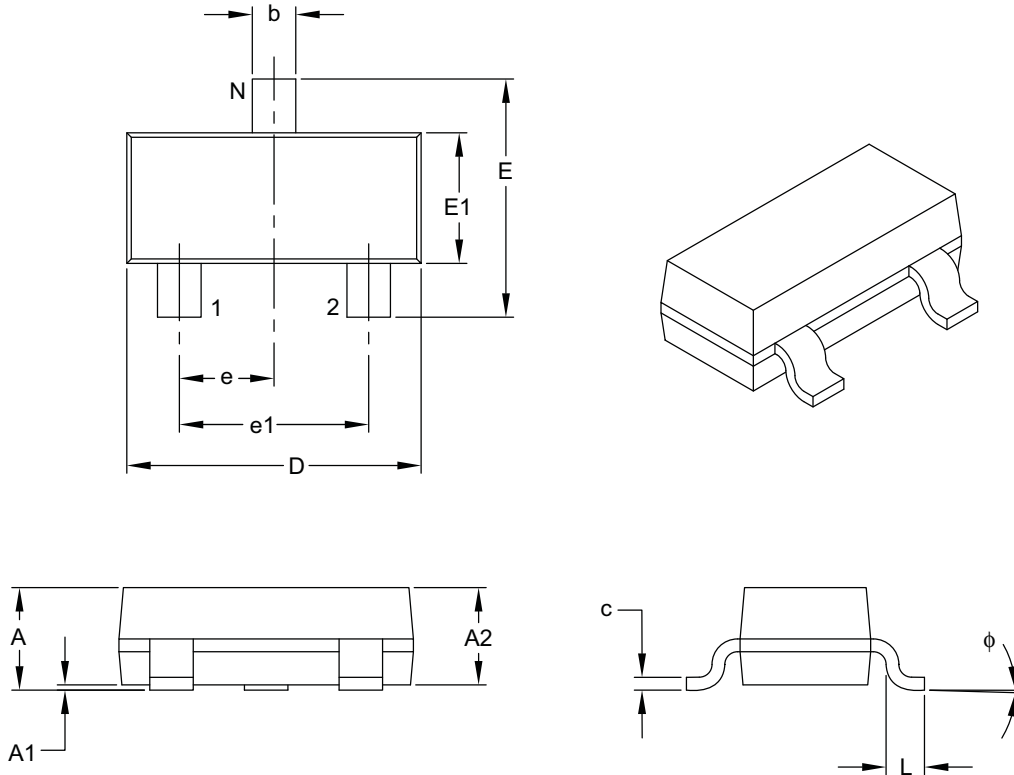
- Dimensions A and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- Dimensioning and tolerancing per ASME Y14.5M.  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-101B

# MCP111/112

## 3-Lead Plastic Small Outline Transistor (TT) [SOT-23]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	3		
Lead Pitch	e	0.95 BSC		
Outside Lead Pitch	e1	1.90 BSC		
Overall Height	A	0.89	–	1.12
Molded Package Thickness	A2	0.79	0.95	1.02
Standoff	A1	0.01	–	0.10
Overall Width	E	2.10	–	2.64
Molded Package Width	E1	1.16	1.30	1.40
Overall Length	D	2.67	2.90	3.05
Foot Length	L	0.13	0.50	0.60
Foot Angle	$\phi$	0°	–	10°
Lead Thickness	c	0.08	–	0.20
Lead Width	b	0.30	–	0.54

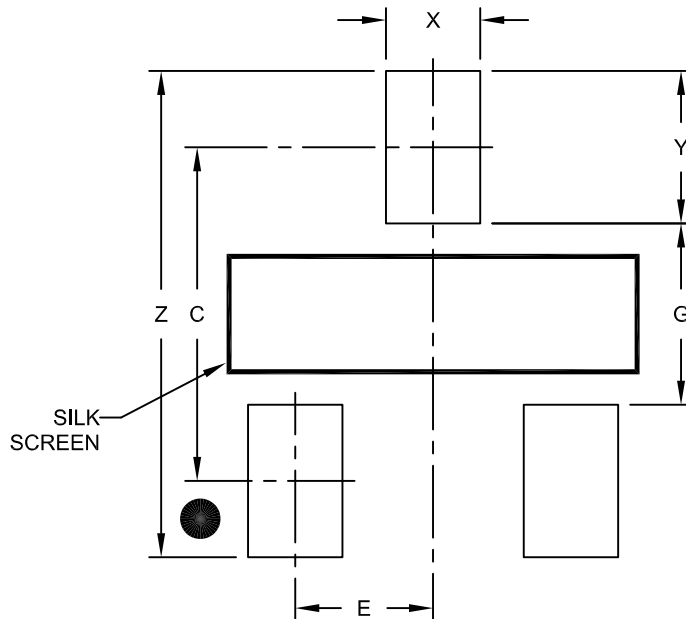
**Notes:**

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-104B

## 3-Lead Plastic Small Outline Transistor (TT) [SOT-23]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.95 BSC		
Contact Pad Spacing	C		2.30	
Contact Pad Width (X3)	X			0.65
Contact Pad Length (X3)	Y			1.05
Distance Between Pads	G	1.25		
Overall Width	Z			3.35

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2104A

# MCP111/112

## 3-Lead Plastic Small Outline Transistor (LB) [SC70]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-060C Sheet 1 of 2

## 3-Lead Plastic Small Outline Transistor (LB) [SC70]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	3		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	-	1.10
Standoff	A1	0.00	-	0.10
Molded Package Thickness	A2	0.80	-	1.00
Overall Length	D	2.00 BSC		
Exposed Pad Length	D2	2.50	2.60	2.70
Overall Width	E	2.10 BSC		
Exposed Pad Width	E1	1.25 BSC		
Terminal Width	b	0.15	-	0.40
Terminal Length	L	0.10	0.20	0.46
Lead Thickness	c	0.20	-	0.26

**Notes:**

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M  
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
 REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-060C Sheet 2 of 2

# MCP111/112

## 3-Lead Plastic Small Outline Transistor (LB) [SC70]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		2.20	
Contact Pad Width	X			0.50
Contact Pad Length	Y			0.85
Distance Between Pads	G	1.25		

Notes:

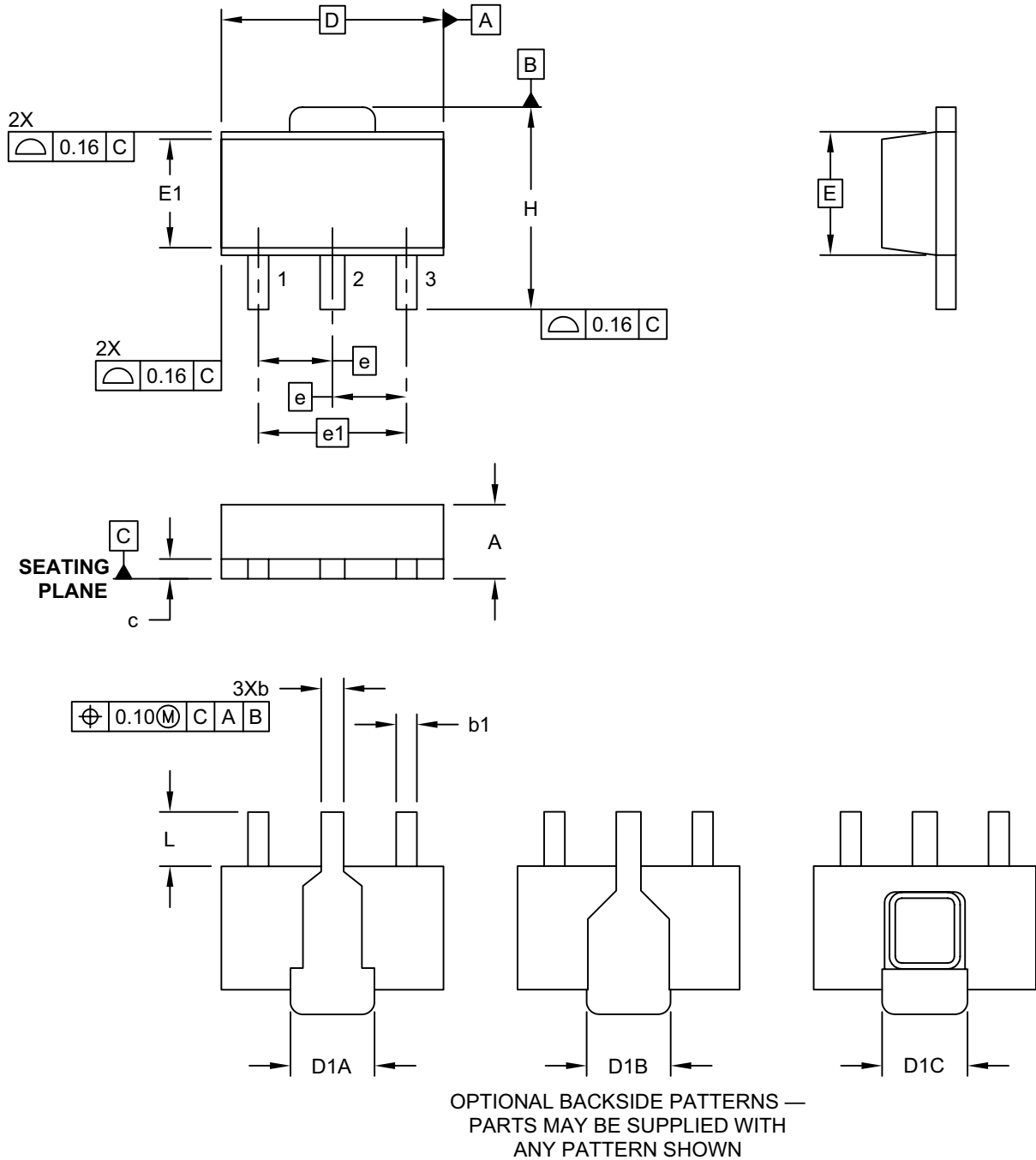
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2060B

## 3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

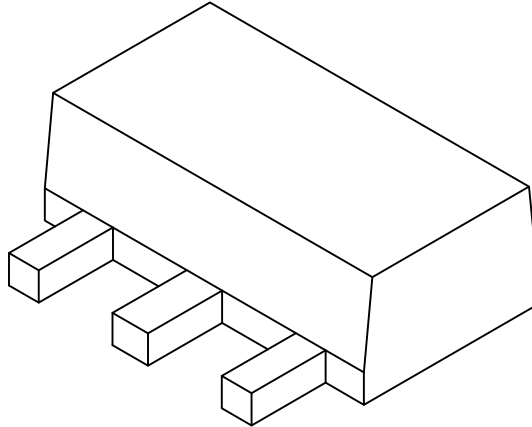


Microchip Technology Drawing C04-029C Sheet 1 of 2

# MCP111/112

## 3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	3		
Pitch	e	1.50 BSC		
Outside Lead Pitch	e1	3.00 BSC		
Overall Height	A	1.40	1.50	1.60
Overall Width	H	3.94	4.10	4.25
Molded Package Width at Base	E	2.50 BSC		
Molded Package Width at Top	E1	2.13	2.20	2.29
Overall Length	D	4.50 BSC		
Tab Length (Option A)	D1A	1.63	1.73	1.83
Tab Length (Option B)	D1B	1.40	1.60	1.75
Tab Length (Option C)	D1C	1.62	1.73	1.83
Foot Length	L	0.79	1.10	1.20
Lead Thickness	c	0.35	0.40	0.44
Lead 2 Width	b	0.41	0.50	0.56
Leads 1 & 3 Width	b1	0.36	0.42	0.48

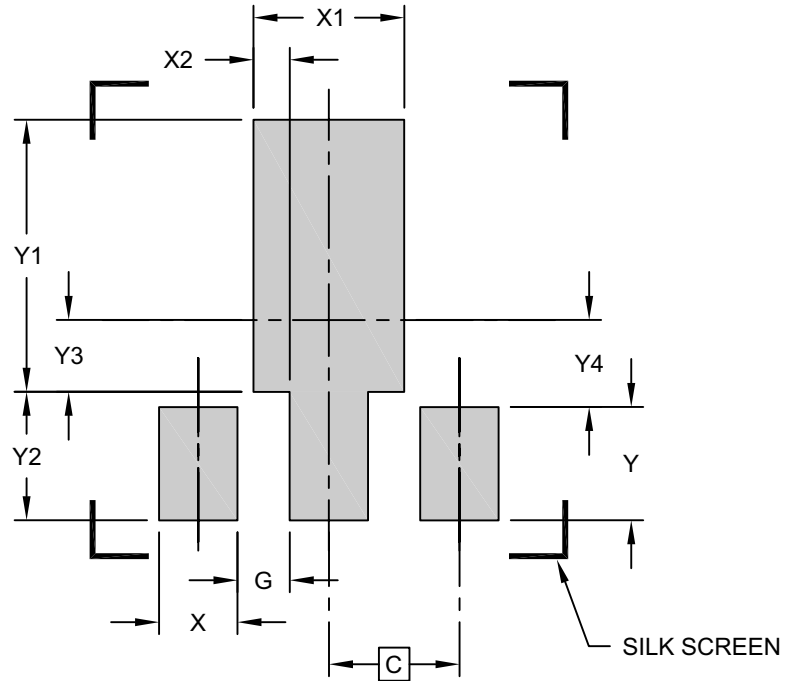
**Notes:**

1. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127mm per side.
2. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-029C Sheet 2 of 2

## 3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

Units	MILLIMETERS		
	MIN	NOM	MAX
C	1.50 (BSC)		
X (3 PLACES)		0.900	
X1		1.733	
X2 (2 PLACES)		0.416	
G (2 PLACES)		0.600	
Y (2 PLACES)		1.300	
Y1		3.125	
Y2		1.475	
Y3		0.825	
Y4		1.000	

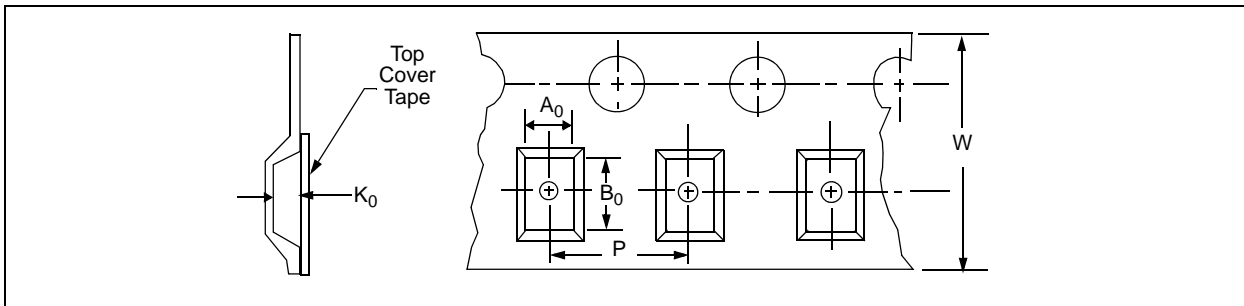
**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2029C

# MCP111/112

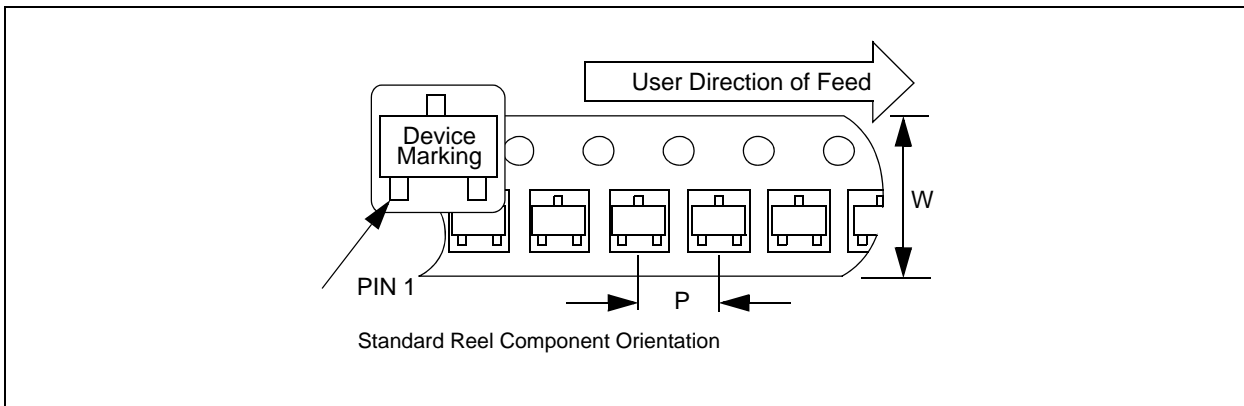
## 5.2 Product Tape and Reel Specifications



**FIGURE 5-1:** Embossed Carrier Dimensions (8, 12, 16 and 24 mm tape only).

### CARRIER TAPE/CAVITY DIMENSIONS

Case Outline	Package Type		Carrier Dimensions		Cavity Dimensions			Output Quantity Units	Reel Diameter in mm
			W mm	P mm	A0 mm	B0 mm	K0 mm		
TT	SOT-23B	3L	8	4	3.15	2.77	1.22	3000	180
LB	SC-70	3L	8	4	2.4	2.4	1.19	3000	180



**FIGURE 5-2:** 3-Lead SOT-23/SC70 Device Tape and Reel Specifications.



**FIGURE 5-3:** TO-92 Devices.



**FIGURE 5-4:** SOT-89 Devices.

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NOTES:

## APPENDIX A: REVISION HISTORY

### Revision F (July 2016)

The following is the list of modifications:

1. Updated [Table 3-1](#).
2. Updated [Section 5.0 “Packaging information”](#).
3. Minor typographical corrections.

### Revision E (January 2013)

- Added a note to each package outline drawing.

### Revision D (June 2005)

1. Added SOT-89-3 package information throughout.

### Revision C (March 2005)

The following is the list of modifications:

1. Added [Section 4.4 “Using in PIC® Microcontroller ICSP™ Applications \(MCP111 only\)”](#) on using the MCP111 in PIC microcontroller ICSP applications.
2. Added  $V_{ODH}$  specifications in [Section 1.0 “Electrical Characteristics”](#) (for ICSP applications).
3. Added Figure 2-28.
4. Added devices features table to page 1.
5. Updated SC-70 package markings and added Pb-free marking information to [Section 5.0 “Packaging information”](#).
6. Added [Appendix A: “Revision History”](#).

### Revision B (August 2004)

1. Corrected package marking information in [Section 5.0 “Packaging information”](#).

### Revision A (May 2004)

- Original release of this document.

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NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>XXX</u>	<u>X</u>	<u>XX</u>
Device	Tape/Reel Option	Monitoring Options	Temperature Range	Package
Device:				
		MCP111: MicroPower Voltage Detector, open-drain		
		MCP111T: MicroPower Voltage Detector, open-drain (Tape and Reel)		
		MCP112: MicroPower Voltage Detector, push-pull		
		MCP112T: MicroPower Voltage Detector, push-pull (Tape and Reel)		
Monitoring Options:		195 = 1.90V		
		240 = 2.32V		
		270 = 2.63V		
		290 = 2.90V		
		300 = 2.93V		
		315 = 3.08V		
		450 = 4.38V		
		475 = 4.63V		
Temperature Range:			I = -40°C to +85°C (MCP11X-195 only)	
			E = -40°C to +125°C (Except MCP11X-195 only)	
Package:				LB = SC-70, 3-lead
				MB = SOT-89, 3-lead
				TO = TO-92, 3-lead
				TT = SOT-23B, 3-lead
<b>Examples:</b>				
a)	MCP111T-195I/TT:	Tape and Reel, 1.95V option, open-drain, -40°C to +85°C, SOT-23B package.		
b)	MCP111T-315E/LB:	Tape and Reel, 3.15V option, open-drain, -40°C to +125°C, SC-70-3 package.		
c)	MCP111-300E/TO:	3.00V option, open-drain, -40°C to +125°C, TO-92-3 package.		
d)	MCP111-315E/MB:	3.15V option, open-drain, -40°C to +125°C, SOT-89-3 package.		
a)	MCP112T-290E/TT:	Tape and Reel, 2.90V option, push-pull, -40°C to +125°C, SOT-23B-3 package.		
b)	MCP112T-475E/LB:	Tape and Reel, 4.75V option, push-pull, -40°C to +125°C, SC-70-3 package.		
c)	MCP112-450E/TO:	4.5V option, push-pull, -40°C to +125°C, TO-92-3 package.		
d)	MCP112-315E/MB:	3.15V option, push-pull, -40°C to +125°C, SOT-89-3 package.		

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NOTES:

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**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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- Microchip is willing to work with the customer who is concerned about the integrity of their code.
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